

Smart eFuse XDP730 and XDP72x

Product Presentation

June 2026

public

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Value proposition to the application provided by Infineon's XDP™ eFuses

Integrated solution

- Smaller application footprint
- Reduction in system BOM
- Minimum external components

Stackable solution

- Capability for current sharing
- Achieving higher output current

High-speed communication

- High accuracy
- Better understanding of energy & power usage
- IMON for load management

Adjustable current limit

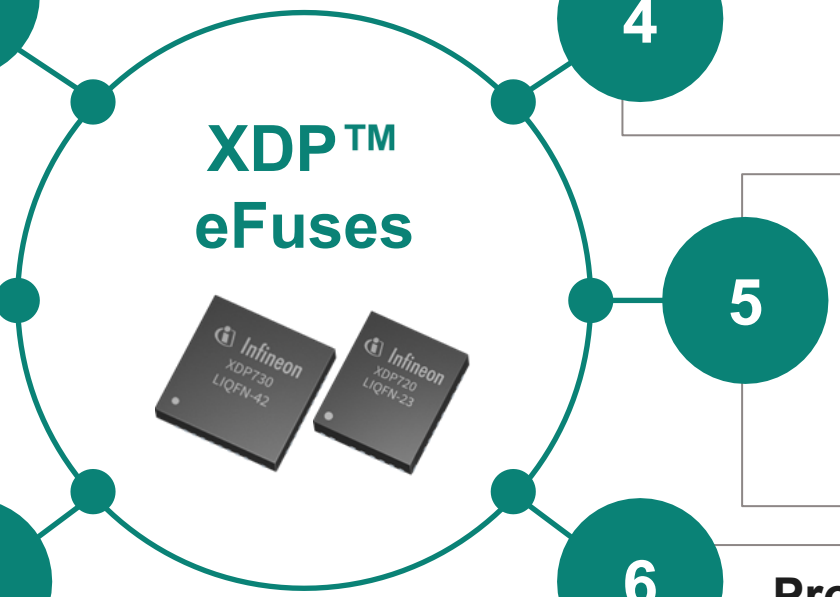
- Enables flexibility in design

Surge Immunity protection

- Differentiation between surge & short-circuit event
- Increased system reliability
- Smooth operation

Protection features

- Robust design
- Along with debugging



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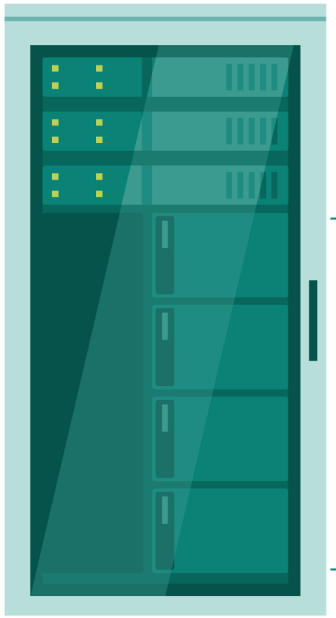
We power AI from grid to core

High performance AI Server for accelerated compute

AI servers

Simplified visualization to showcase Infineon content in an exemplary AI server with accelerator cards. Configurations may vary.



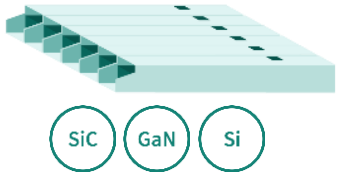
per rack

per rack

per rack



Top of rack switch



Power Supply Unit



Battery Back-up Unit



Chassis

for one AI server

Baseboard /
GPU OAM cards





48 V Bus Converter



AI card (power stages or vertical modules)

PCIE Board





Smart Network Interface Cards

Motherboard





Server motherboard

Power system reliability modeling possible on every controller

Infineon protection chips available (hot swaps, eFuses)

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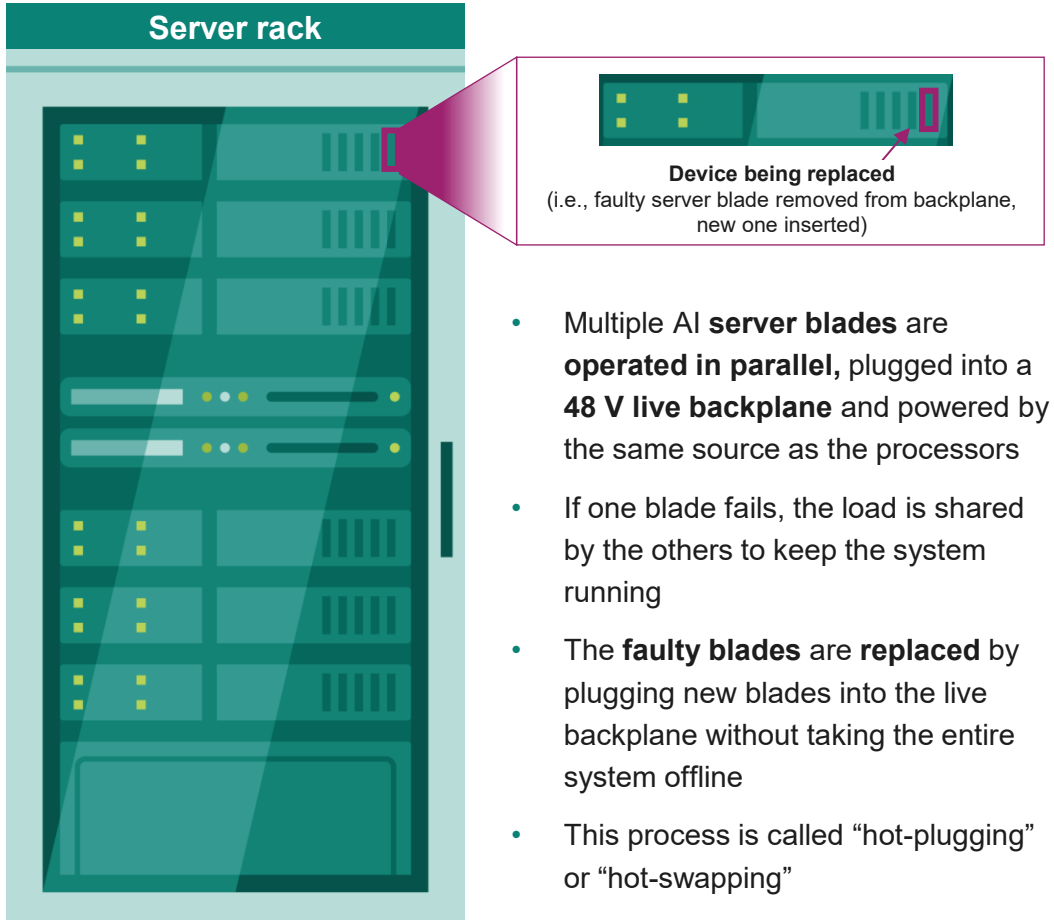
Infineon protection chips - We power and protect AI

Introduction to hot-swapping in data centers and servers

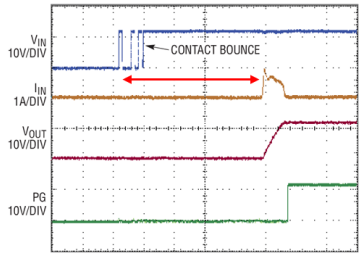
What is hot-swapping?

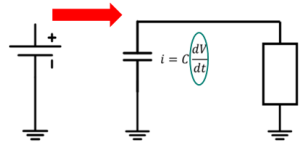


- Multiple AI **server blades** are **operated in parallel,** plugged into a **48 V live backplane** and powered by the same source as the processors
- If one blade fails, the load is shared by the others to keep the system running
- The **faulty blades** are **replaced** by plugging new blades into the live backplane without taking the entire system offline
- This process is called “hot-plugging” or “hot-swapping”

What are the key pain points?

- Servers and data centers need to be **always online** due to 24/7 usage, which requires an **interruption-free operation**
- Since **system level failures** can occur, server trays must be protected to **avoid this costly server downtime** or **high replacement costs**
- Hot-plugging a server blade creates **inrush current**, strong enough to blow up the fuse or cause voltage dips in adjacent trays, thus triggering a system shutdown
- As well, **contact bouncing** occurs when the server blade is mechanically inserted into the live backplane, requiring a debouncing-window to make sure the blade is securely plugged-in
- In addition to hot-swap controllers, **electronic fuses (eFuses)** are new and **highly efficient solutions** for hot-swap applications, **protecting against failures**, providing **highly-accurate monitoring and telemetry while saving PCB space** through integration







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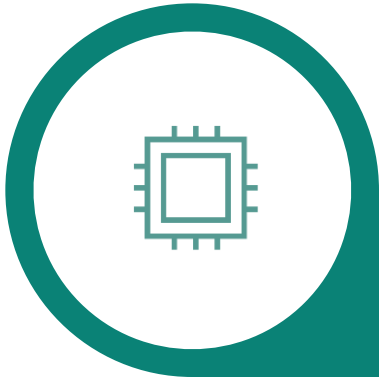
Addressing key market and application trends and requirements



Size

- Rising GPU performance increases its size & power, while form factor remains constant/ shrinks, leading to **less space for power components**
- **[IMPACT]**
  1. MOSFETs with **better R_{on}*A** to reduce losses and possibly avoid paralleling
  2. Need for **small packages**
  3. **Integration** of components to save PCB space



Reliability

- Unplanned server down-time is very expensive with multiple other implications
- High thermal stress due to density and high current levels; tough environmental conditions require **high reliability for the devices**
- **[IMPACT]**
  1. **Embedded telemetry** to monitor accumulated stress conditions
  2. “Manipulate” extensive telemetry information & support **predictive maintenance**



Thermal design & peak power

- Rising GPU/ASIC performance leads to increasing energy consumption over time
- More computational performance requires more power in the same/less space
- **[IMPACT]**
  1. Topologies which allow **better efficiency** & **high power density**
  2. Efficient power devices with **enhanced packaging**
  3. Drivers with **high-speed operation** & good **thermal performance**

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How Infineon's digital eFuses XDP730, XDP720, XDP721 & XDP722 bring value to its target applications

48 V / 54 V
(AI) server & data center



24 V / 48 V
industrial systems



Fan tray /
Fan control



- ✓ Integration of FET, current sensor, and controller into a single package results in **smaller application footprint** & **reduced system BOM**
- ✓ Adjustable current limit ensures **flexibility in design**
- ✓ Extensive protection features enable a highly robust and reliable system design along with debugging
- ✓ Current sharing to achieve **higher output current** by stacking multiple eFuses
- ✓ Suitable for **high voltage compliant system designs** (IPC2221B & IPC9592B)

- V_{IN} operating range up to 80 V
- Low $R_{DS(on)}$ FET 30A 1.3 mΩ or 20 A 3.0 mΩ
- Active SOA & Surge Immunity protection
- PMBus® v1.3 interface @ 1MHz
- Programmable fault response: auto-retry, latch-off
- LIQFN-42 7x7 or LIQFN-23 6x5 package

- Wide V_{IN} operating range 7 V to 80 V
- Low $R_{DS(on)}$ FET 30 A 1.3 mΩ or 20 A 3.0 mΩ
- Active SOA & Surge Immunity protection
- PMBus® v1.3 interface @ 1MHz
- LIQFN-42 7x7 or LIQFN-23 6x5 package

- Wide V_{IN} operating range 7 V to 80 V
- Low $R_{DS(on)}$ FET 20 A, 3.0 mΩ
- Active SOA protection
- Fault response: Auto-retry (XDP722) or latch-off (XDP721)
- LIQFN-23 6x5 package

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How Infineon's XDP7xx digital eFuses are positioned in the Protection IC family

XDP™ Protection ICs

Digital eFuse

NEW

XDP730-001 *	XDP720-001 *
XDP721-001 *	XDP722-001 *

Key differentiating features of the product family:

- Wide input voltage range +7 V to +80 V
- Integrated hot-swap controller, low $R_{DS(on)}$ FET 30 A or 20 A, and current sensor
- With/without PMBus® for accurate telemetry: 1 MHz
- Analog current monitoring
- Superior reporting accuracy V≤0.5 %, I≤1 %, P≤2%, E≤3%
- Extensive protection features
- Small footprint LIQFN-42 7x7 or LIQFN-23 6x5

Monitoring IC

NEW

XDM700-1 *

Key differentiating features of the product family:

- Wide input voltage range +5 V to +80 V
- Integrated 5 V regulator
- High/low-side current sensing
- PMBus® for highly accurate telemetry: 1MHz
- Analog current & power monitoring
- Superior reporting accuracy V≤0.4%, I≤0.75%, P≤1.15%, E≤2.7%
- Programmable alerts: OC, OV, UV, OP, OT
- Small footprint VQFN-24 4x4

Hot-swap controller

XDP711-001	XDP710-002
XDP710-001	XDP700-002

Key differentiating features of the product family:

- Wide input voltage range up to +80 V
- Integrated gate driver, drive capability up to 250 µA
- Pulsed SOA current control (Boost Mode) technology for safer turn-on
- PMBus® for highly accurate telemetry: 1MHz
- Superior reporting accuracy V≤0.4%, I≤0.75%, P≤1.15%, E≤2.7%
- Extensive protection features
- Small footprint VQFN-29 6x6

* Coming soon est. 2026 Q1 (eFuse) and 2025 Q4 (Monitoring IC)

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Infineon's XDP™ eFuse value propositions

Portfolio summary

XDP730*



XDP72x*

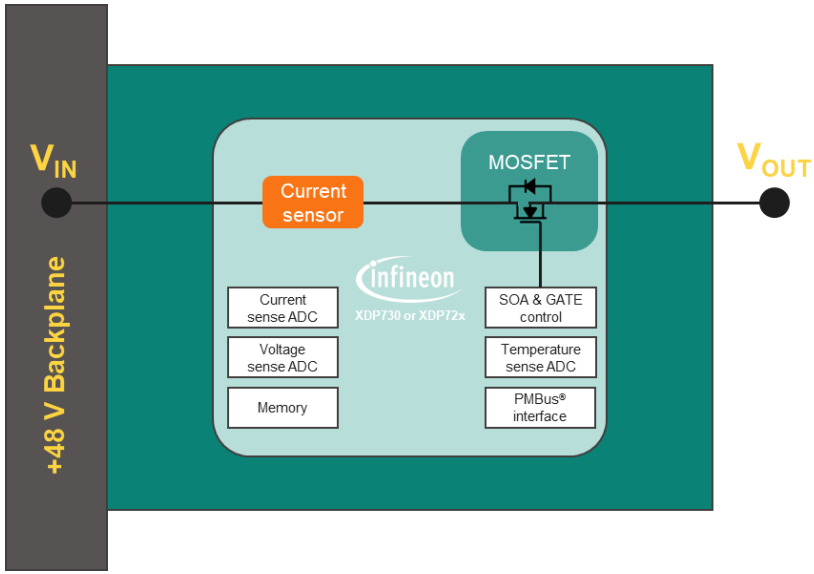


- Integrated hot-swap controller, current sensor, and low $R_{DS(on)}$ OptiMOS™ FET in a single package (LIQFN 7x7 or 6x5)
- Up to 30 A (1.3 mΩ) or 20 A (3.0 mΩ) continuous current carrying capability for a wide operating V_{IN} range of +7 V to +80 V
- Active monitoring and reporting accuracy: V ≤ 0.5 %, I ≤ 1 %, P ≤ 2%, E ≤ 3%
- Input voltage Surge Immunity to increase system reliability and a smooth operation

Value proposition

1. Integration for **smaller application footprint** and **reduction in system BOM** with minimum external components
2. Stackable so that it is capable for **current sharing** to achieve **higher output current**
3. High-speed communication via PMBus® for **high accuracy**, better **understanding of energy and power usage**, and IMON capability for **load management**
4. Adjustable current limit for **flexibility in design**
5. Increases **system reliability** & enables **smooth operation** by differentiating between surge and short-circuit (Surge Immunity)
6. Extensive protection features for **robust design** along with debugging
7. Non-volatile memory (OTP) for **multi-level system configuration**
8. IPC2221B & IPC9592B **high-voltage compliant**, suitable for HV compliant system designs

Simplified block diagram



* Coming soon

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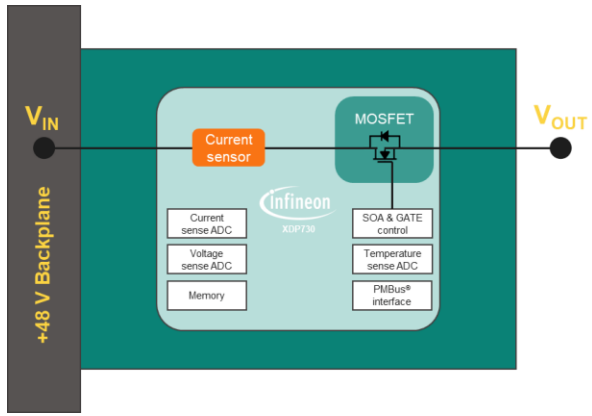
XDP™ digital eFuse XDP730-001 overview

Product highlights

- Input voltage Surge Immunity (gate boost for fast recovery from induced OC transients)
- Active SOA protection
- "Primary/Standalone" or "Secondary" device operation mode for stacking multiple eFuses
- Dedicated current and voltage ADCs: **12-bit** resolution**, ~102.4 µs** refresh rate
- Dedicated internal die-temperature sensors
- Active monitoring and reporting: **V ≤ ±0.5 %, I ≤ ±1 %, P ≤ ±2%, E ≤ ±3%**
- Analog current (IMON) monitoring/reporting pin with up to **≥ ±1% accuracy**
- Programmable Over-Current (OC), Severe Over-Current (SOC), Over-Voltage (OV), Under-Voltage (UV), Watchdog (WD), FET Health, Over-Temperature (OT, TSD) & VDS protections
- Permanent PMBUS WRITE protection
- One Time Programmable non-volatile configuration

Typical application diagram





LIQFN-42 7x7 mm

Key specifications

P/N	V_{IN} range	Current rating	$R_{DS(on)}$ (typ.)	Communication interface	Monitoring accuracy	Fault response
XDP730-001	**+7 V to +80 V**	**30 A**	**1.3 mΩ**	**PMBus® v1.3 @ 1MHz**	**V ≤ ±0.5 % I ≤ ±1 %**	**Auto-retry, latch-off**
XDP720-001		20 A	3.0 mΩ			
XDP721-001				-	-	Latch-off
XDP722-001				-	-	Auto-retry

Typical applications

- 48 V/54 V Servers and Datacenters
- AI server cards
- 24 V/48 V Industrial Systems
- Power Distribution Systems
- Network Routers and Switches
- Power Supplies
- Test Equipment



Product information

- XDP730-001 product page
- Protection and Monitoring ICs family page
- EVAL_XDP730-001 evaluation board page

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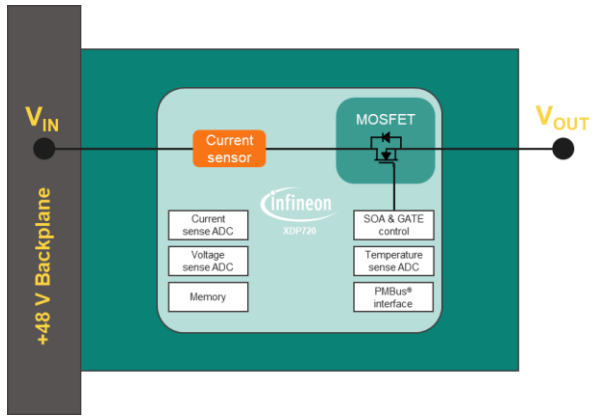
XDP™ digital eFuse XDP720-001 overview

Product highlights

- Input voltage Surge Immunity (gate boost for fast recovery from induced OC transients)
- Active SOA protection
- "Primary/Standalone" or "Secondary" device operation mode for stacking multiple eFuses
- Dedicated current and voltage ADCs: **12-bit** resolution**, ~102.4 µs** refresh rate
- Dedicated internal die-temperature sensors
- Active monitoring and reporting: **V ≤ ±0.5 %, I ≤ ±1 %, P ≤ ±2%, E ≤ ±3%**
- Analog current (IMON) monitoring/reporting pin with up to **≥ ±1% accuracy**
- Programmable Over-Current (OC), Severe Over-Current (SOC), Over-Voltage (OV), Under-Voltage (UV), Watchdog (WD), FET Health, Over-Temperature (OT, TSD) & VDS protections
- Permanent PMBUS WRITE protection
- One Time Programmable non-volatile configuration

Typical application diagram





LIQFN-23 6x5 mm

Key specifications

P/N	V_{IN} range	Current rating	$R_{DS(on)}$ (typ.)	Communication interface	Monitoring accuracy	Fault response
XDP730-001	**+7 V to +80 V**	30 A	1.3 mΩ	**PMBus® v1.3 @ 1MHz**	**V ≤ ±0.5 % I ≤ ±1 %**	**Auto-retry, latch-off**
XDP720-001		**20 A**	**3.0 mΩ**			
XDP721-001				-	-	Latch-off
XDP722-001				-	-	Auto-retry

Typical applications

- 48 V/54 V Servers and Datacenters
- Fan control
- 24 V/48 V Industrial Systems
- Power Distribution Systems
- Network Routers and Switches
- Power Supplies
- Test Equipment



Product information

- XDP720-001 product page
- Protection and Monitoring ICs family page
- EVAL_XDP72X-001 evaluation board page

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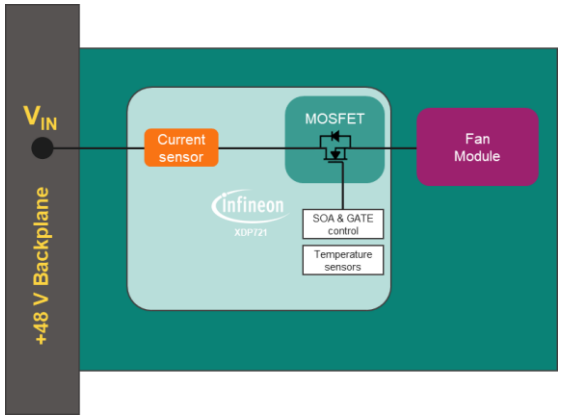
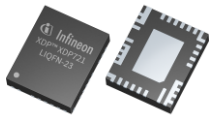
XDP™ digital eFuse XDP721-001 overview

Product highlights

- Input voltage Surge Immunity (gate boost for fast recovery from induced OC transients)
- Active SOA protection
- "Primary/Standalone" or "Secondary" device operation mode for stacking multiple eFuses
- Dedicated current and voltage ADCs: **12-bit** resolution**, ~102.4 µs** refresh rate
- Dedicated internal die-temperature sensors
- Analog current (IMON) monitoring/reporting pin with up to **≥ ±1% accuracy**
- Programmable Over-Current (OC), Severe Over-Current (SOC), Over-Voltage (OV), Under-Voltage (UV), Watchdog (WD), FET Health, Over-Temperature (OT, TSD) & VDS protections
- One Time Programmable non-volatile configuration

Typical application diagram





LIQFN-23 6x5 mm

Key specifications

P/N	V_{IN} range	Current rating	$R_{DS(on)}$ (typ.)	Communication interface	Monitoring accuracy	Fault response
XDP730-001	**+7 V to +80 V**	30 A	1.3 mΩ	PMBus® v1.3 @ 1MHz	V ≤ ±0.5 % I ≤ ±1 %	Auto-retry, latch-off
XDP720-001		**20 A**	**3.0 mΩ**			
XDP721-001				**-**	**-**	**Latch-off**
XDP722-001				-	-	Auto-retry

Typical applications

- 48 V/54 V Servers and Datacenters
- Fan tray
- 24 V/48 V Industrial Systems
- Power Distribution Systems
- Network Routers and Switches
- Power Supplies
- Test Equipment



Product information

- XDP721-001 product page
- Protection and Monitoring ICs family page
- EVAL_XDP72X-001 evaluation board page

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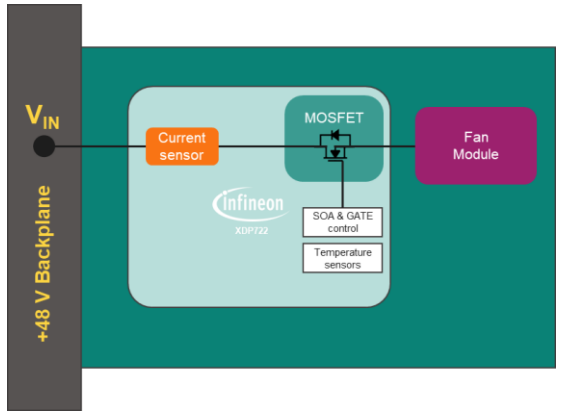
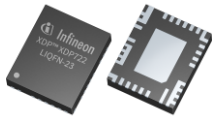
XDP™ digital eFuse XDP722-001 overview

Product highlights

- Input voltage Surge Immunity (gate boost for fast recovery from induced OC transients)
- Active SOA protection
- "Primary/Standalone" or "Secondary" device operation mode for stacking multiple eFuses
- Dedicated current and voltage ADCs: **12-bit** resolution**, ~102.4 µs** refresh rate
- Dedicated internal die-temperature sensors
- Analog current (IMON) monitoring/reporting pin with up to **≥ ±1% accuracy**
- Programmable Over-Current (OC), Severe Over-Current (SOC), Over-Voltage (OV), Under-Voltage (UV), Watchdog (WD), FET Health, Over-Temperature (OT, TSD) & VDS protections
- One Time Programmable non-volatile configuration

Typical application diagram





LIQFN-23 6x5 mm

Key specifications

P/N	V_{IN} range	Current rating	$R_{DS(on)}$ (typ.)	Communication interface	Monitoring accuracy	Fault response
XDP730-001	**+7 V to +80 V**	30 A	1.3 mΩ	PMBus® v1.3 @ 1MHz	V ≤ ±0.5 % I ≤ ±1 %	Auto-retry, latch-off
XDP720-001		**20 A**	**3.0 mΩ**			
XDP721-001				-	-	Latch-off
XDP722-001				**-**	**-**	**Auto-retry**

Typical applications

- 48 V/54 V Servers and Datacenters
- Fan tray
- 24 V/48 V Industrial Systems
- Power Distribution Systems
- Network Routers and Switches
- Power Supplies
- Test Equipment



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XDP™ Protection IC portfolio – differentiation of product variants and product types

See next slide for details

See next slides for details

P/N	Product type	Input operating voltage [V]	Current rating [A]	$R_{DS(on)}$ (typ.) [mΩ]	Communi-cation interface	Monitoring accuracy	Fault response	Modes of operation [1]	Surge Immunity	Analog monitoring	Protection Features
XDP730-001 *	eFuse	+7 to +80	30	1.3	PMBus® v1.3	V≤0.5%, I≤1%, P≤2%, E≤3%	Programmable	FDM	Yes	Current	Programmable overcurrent (OC), severe overcurrent (SOC), overvoltage (OV), undervoltage (UV), Watchdog (WD), FET health, over temperature (OT, TSD), VDS protections
XDP720-001 *	eFuse	+7 to +80	20	3.0	PMBus® v1.3	V≤0.5%, I≤1%, P≤2%, E≤3%	Programmable	FDM	Yes	Current	Programmable overcurrent (OC), severe overcurrent (SOC), overvoltage (OV), undervoltage (UV), Watchdog (WD), FET health, over temperature (OT, TSD), VDS protections
XDP721-001 *	eFuse	+7 to +80	20	3.0	-	-	Latch-off	Analog	-	Current	Overcurrent (OC), severe overcurrent (SOC), overvoltage (OV), undervoltage (UV), Watchdog (WD), FET health, over temperature (OT, TSD), VDS protections
XDP722-001 *	eFuse	+7 to +80	20	3.0	-	-	Auto-retry	Analog	-	Current	Overcurrent (OC), severe overcurrent (SOC), overvoltage (OV), undervoltage (UV), Watchdog (WD), FET health, over temperature (OT, TSD), VDS protections
XDM700-1 *	V/I Monitor	+5 to +80	-	-	PMBus® v1.3	V≤0.4%, I≤0.75%, P≤1.15%, E≤2.7%	-	FDM	-	Current, Power	-
XDP711-001	Hot-swap controller	+7 to +80	-	-	PMBus® v1.3	V≤0.4%, I≤0.75%, P≤1.15%, E≤2.7%	Limiting, auto-retry, latch-off	FDM, AADM, Hybrid	Yes	Current, Power	Two-level adjustable overcurrent (OC & SOC), programmable overvoltage (OV), undervoltage (UV), over temperature (OT, diode sense) protections
XDP710-002	Hot-swap controller	+5.5 to +80	-	-	PMBus® v1.3	V≤0.4%, I≤0.75%, P≤1.15%, E≤5%	Auto-retry, latch-off	FDM, AADM	-	-	Overcurrent (OC), overvoltage (OV), undervoltage (UV), Watchdog timer, FET faults, memory and SOA fault, over temperature (OT, diode sense) protections
XDP700-002	Hot-swap controller	-6.5 to -80	-	-	PMBus® v1.3	V≤0.5%, I≤1.3%, P≤1.8%, E≤5%	Auto-retry, latch-off	FDM, AADM	-	.	Overcurrent (OC), overvoltage (OV), undervoltage (UV), Watchdog timer, FET faults, memory and SOA fault, over temperature (OT) protections

* Coming soon

1) FDM = Fully Digital Mode; AADM = Analog Assisted Digital Mode

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Feature description
PMBus® for high-speed communication and accurate telemetry

- Supports PMBus® communication up to **1 MHz**, i.e., telemetry register can be read within 50 µs
- Superior **voltage** (V ≤ 0.5%), **current** (I ≤ 1%), **power** (P ≤ 2%) and **energy** (E ≤ 3%) **reporting accuracy**
  - Voltage (V) is measured by ADC
  - Current (I) is measured by current mirror and voltage on IMON pin
  - Power is calculated by P = V x I
  - Energy (E = ∫VIdt) is calculated from voltage and current
- **12-bit** ADC with telemetry data available every **102.4 µs**

Value proposition

- The high telemetry accuracy and high speed of communications allows the user to **monitor the health of eFuses reliably in real time**
- High speed communication allows the device to be **used as a digital oscilloscope** to see the voltage and current behavior
- The highly accurate energy telemetry allows the customers to **rely on this data to monitor the energy usage** of the server without any expensive and bulky external energy meter

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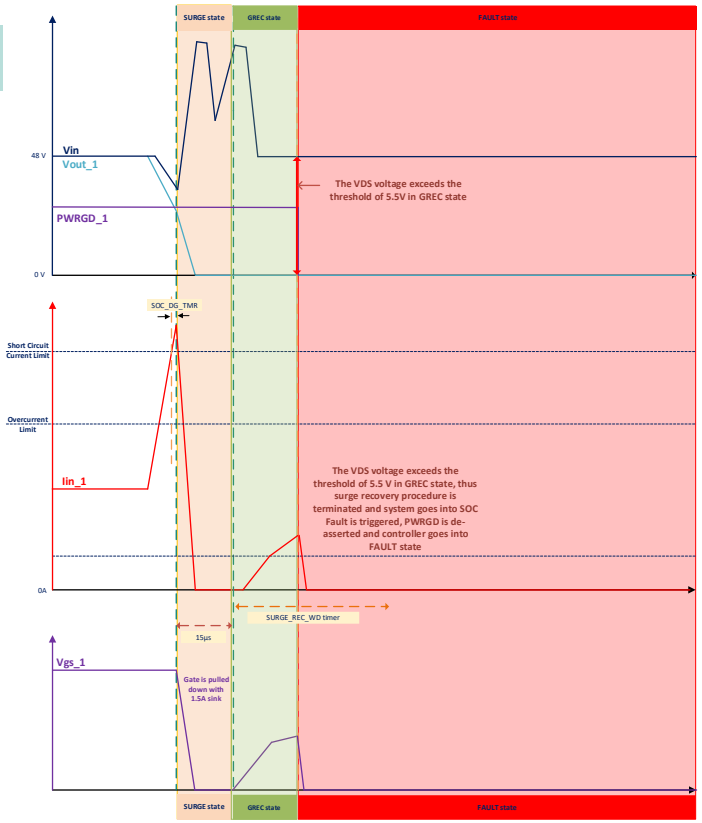
Feature description
Surge Immunity

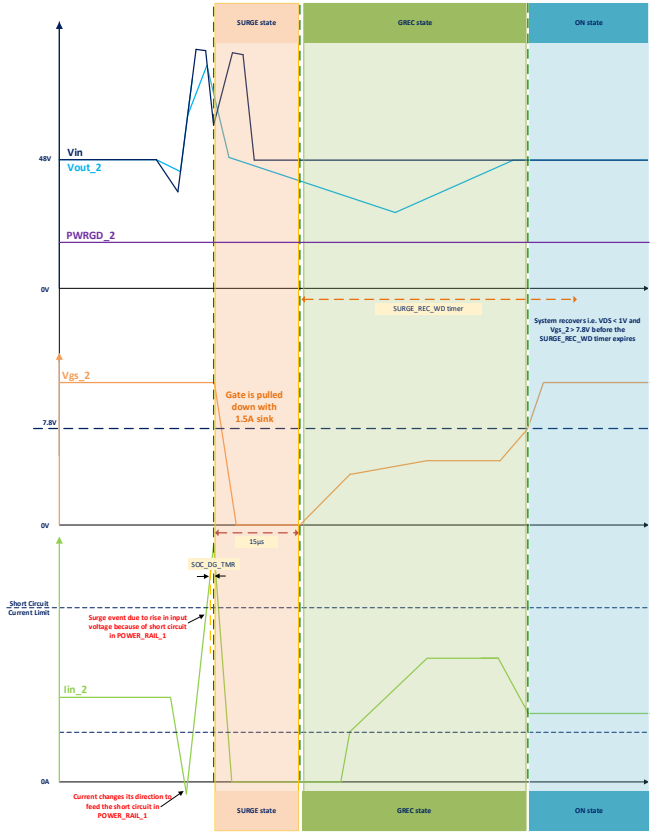
- Surge immunity increases the **availability of the system** by **differentiating** between an **input voltage surge** and a **short circuit event,** using surge watchdog timer, fast output under voltage detection and VDS detection.

Surge Immunity vs. short circuit

Short circuit



Surge event



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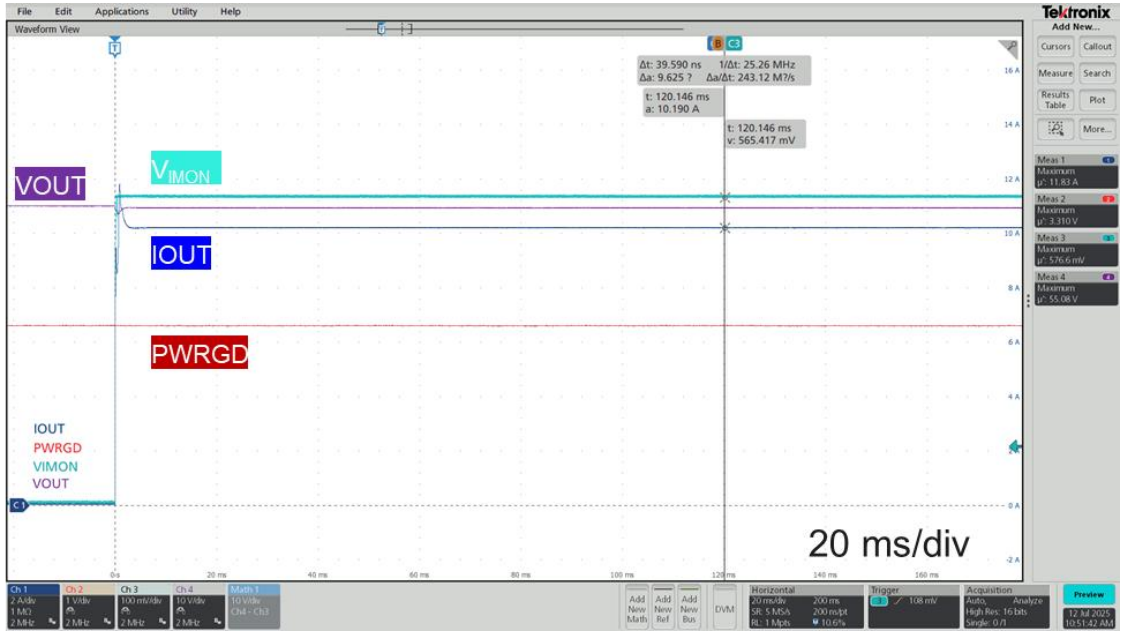
Feature description
Analog current monitoring (IMON) capability

- The eFuses XDP730 and XDP72x offer the most accurate analog current which **reduces the latency of the availability of this data onto the host controller** as instead of using PMBus® to read this data continuously, now the data is available with 1 MHz bandwidth
- This information can also be utilized by other downstream controllers to offer **better dynamic response** or **management of load current**

IMON waveforms



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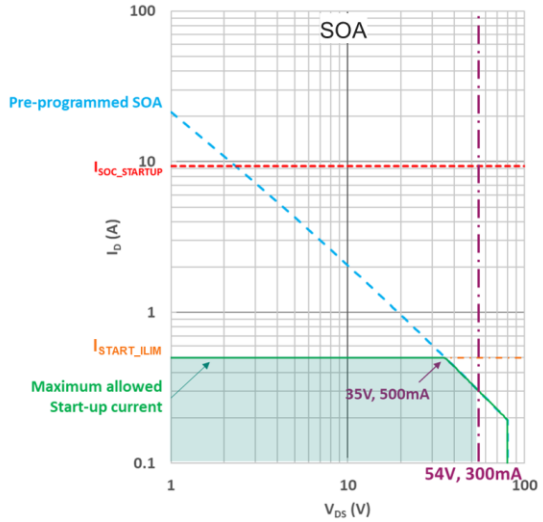
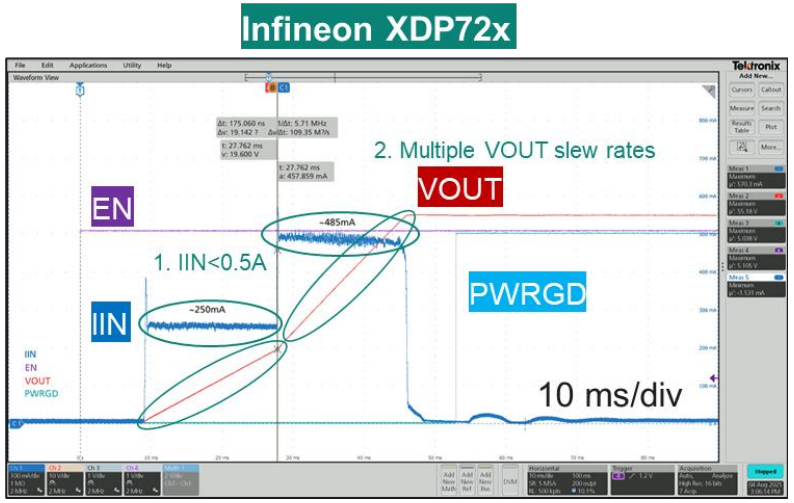
Feature description
Safe Operating Area (SOA) control

- eFuses XDP730 and XDP72x offer **SOA control** which **limits the current** that flows through the **integrated power FET** based on the measured VDS voltage
- With SOA control, **different current levels at different VDS levels can be programmed** which allows for the **faster turn-off of the FET within the safe SOA limits**, if the load current gets applied to it at start-up, then will limit the current to programmed limit

SOA waveform of inrush current control at start-up

- Comparing IIN current and VOUT at start-up, Infineon eFuse strictly respects the SOA line





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Boards overview
XDP™ eFuses

** Coming soon*

EVAL_XDP730-001 *

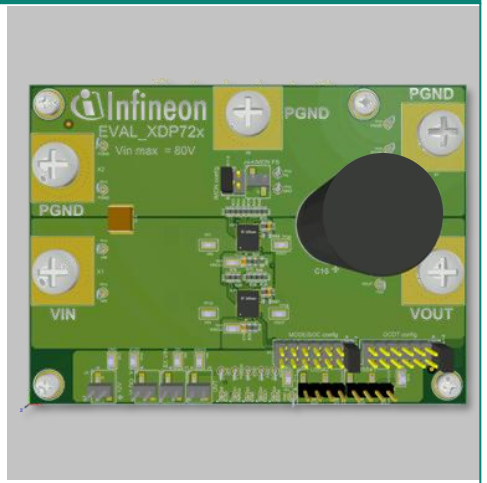
- Features **XDP730 eFuse** with integrated digital controller, current sensor and a low $R_{DS(on)}$ (1.3 mΩ) OptiMOS™ FET with up to 30 A continuous current carrying capability
- Current sharing to achieve higher output current
- To evaluate XDP730 with three/two eFuses in parallel, or single eFuse
- Port for XDP™ Designer dongle
- Configurable 3.3 V/5 V bias
- On board I^2C pull-ups



More information and user manual are available [here].

EVAL_XDP72X-001 *

- Features **XDP720** (with PMBus®) and/or **XDP721/722** (w/o PMBus®) eFuse with integr. digital controller, current sensor and a low $R_{DS(on)}$ (3.0 mΩ) OptiMOS™ FET with up to 20 A continuous current carrying capability
- Current sharing to achieve higher output current
- One single EVAL board to evaluate XDP720/721/722 or combinations
- Port for XDP™ Designer dongle
- Configurable 3.3 V/5 V bias
- On board I2C pull-ups



More information and user manual are available [here].

Evaluation board

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Boards overview
XDP™ hot-swap controller

EVAL_XDP711-001 [EVALXDP711001TOBO1]

- Features the wide input voltage range digital hot-swap controller **XDP™ XDP711-001** to provide a controlled turn-on of the FETs to reduce the inrush current on capacitive load
- In conjunction with the module EVAL_XDP7xx_FET_BRD_mTOLL, it allows for **testing the turn-on behavior of one or multiple (parallel) N-channel MOSFETs**

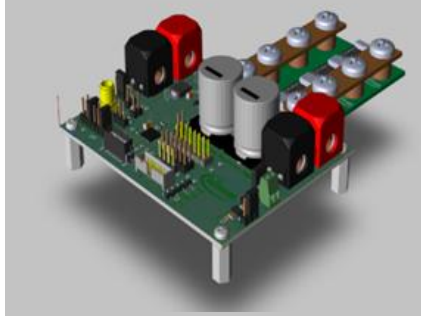
More information and user manual are available [here].



EVAL_XDP710_V2 [EVALXDP710V2TOBO1]

- This board features the XDP710-002, a wide input voltage range Hot-swap controller to provide controlled turn-on of the FETs to reduce the inrush current on capacitive load.
- In conjunction with the module EVAL_XDP710_FET, it allows for **testing of controlled turn-on of N-Channel MOSFETs** in various footprints with option to add multiple FETs in parallel for higher power levels.

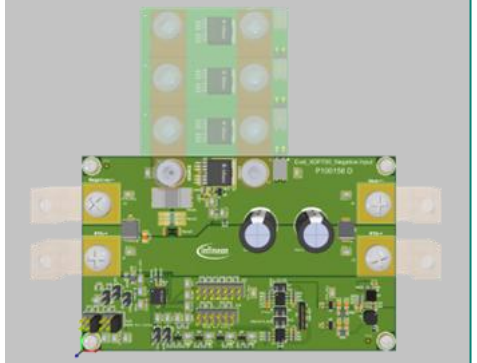
More information and user manual are available [here].



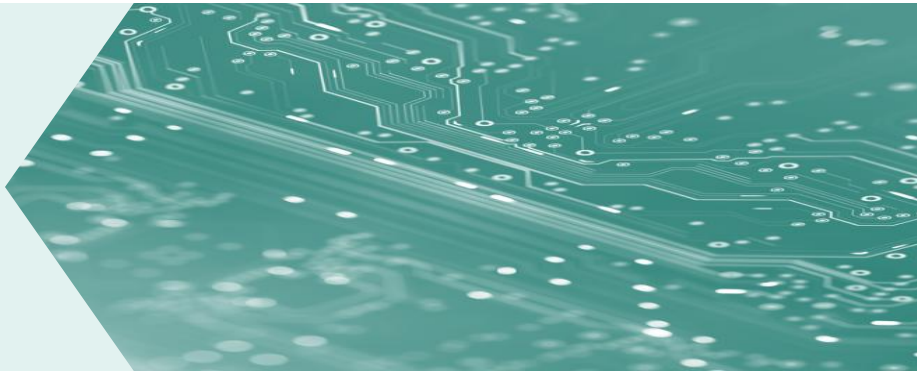
EVAL_XDP700 [EVALXDP700TOBO1]

- Features the **XDP700-002**, a wide input voltage range (-6.5 to -80V) hot-swap controller to provide controlled turn-on of the FETs to reduce the inrush current on capacitive load
- It allows for **testing of controlled turn-on of N-Channel MOSFETs** in various footprints with option to add multiple FETs in parallel for higher power levels

More information and user manual are available [here].



Evaluation board



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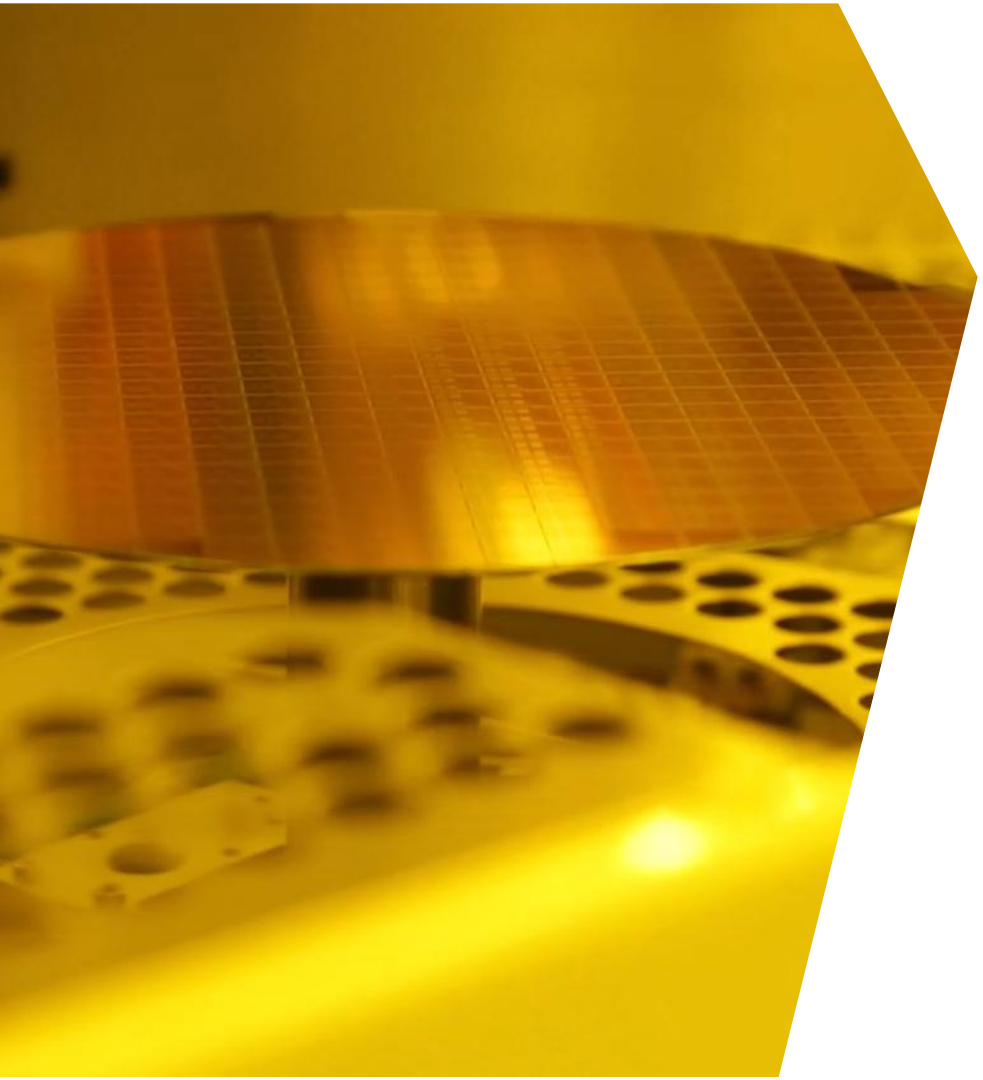
Protection and monitoring IC product status



Product status

XDP730-001 ***(coming soon)***

- M9 release: Jul'26
- **ES available now**
- Evaluation board + GUI: available
- Link to webpage

XDP72x-001 ***(coming soon)***

- M9 release: Jul'26
- **ES available now**
- Evaluation board + GUI: available
- Link to webpage XDP720, XDP721, XDP722

XDM700-001 (A31) ***(coming soon)***

- M9 release: Jul'26
- **ES available now**
- Evaluation board + GUI: available
- Link to webpage

XDP711-001 (A31) ***(recommended for new designs)***

- M9 released Jul'25
- Evaluation board + GUI: available
- Link to webpage

XDP710-002 (A21) ***(recommended for new designs)***

- M9 released Dec'23
- Evaluation board + GUI: available
- Link to webpage

XDP710-001 (A11) ***(not recommended for new designs)***

- M9 released Nov'22
- Evaluation board + GUI: available
- Link to webpage

XDP700-002 (A21) ***(recommended for new designs)***

- M9 released Dec'23
- Evaluation board + GUI: available
- Link to webpage

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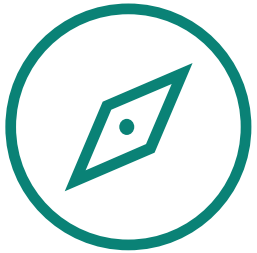
Get started today with resources at your fingertips!



Product and application information

- Product family page: Protection and Monitoring ICs
- Product pages: XDP730 | XDP720 | XDP721 | XDP722
- Target application pages: (AI) server & data center | Humanoid Robots

Reference designs & boards

- Evaluation boards: EVAL_XDP730-001 | EVAL_XDP72X-001
- Software tools & simulations: XDP™ Designer GUI

Technical documents

- Application Note
- User Guide EVAL_XDP730-001 | EVAL_XDP72X-001
- Technical articles about hot-swap controllers (Bodo's Power), eFuses (PSD, Dec'25 issue)

Videos and podcasts

- Protection IC podcast [YouTube]
- Protection IC podcast [Podbean]

Trainings

- Webinars tbd.
- Online training tbd.

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